

L Number	Hits	Search Text	DB	Time stamp
2	127	(micro\$needle\$2 micro\$hypodermic\$2) and ((\$1mu\$1m) with (long length width wide diameter))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 17:35
3	144	(etching etch etched) with silicon with tolerance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 16:10
16	33	(etch\$3 etch etched) with silicon with (micron micrometer) with (" + / -" "+/-" tolerance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 16:49
17	1	(etch\$3 etch etched) with ((silicon with nitride) (potassium hydroxide)) with (micron micrometer) with (" + / -" "+/-")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 16:55
18	63	(etch\$3 etch etched) same ((silicon with nitride) (potassium hydroxide)) same tolerance same (micrometer " + / -" "+/-" micron)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 16:56
19	111	(etch\$3 etch etched) same (silicon with nitride) same (potassium hydroxide) same (tolerance micron " + / -" "+/-" micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 17:07
23	80	((sampl\$3 collect\$3 collection) with (micro\$needle\$2 micro\$hypodermic\$2 needle hypodermic)) same ((\$1mu\$1m micron micrometer "1 millimeter" "one millimeter") with (long length))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 18:23
24	176	((sampl\$3 collect\$3 collection) with (micro\$needle\$2 micro\$hypodermic\$2 needle hypodermic)) and ( (micro\$needle\$2 micro\$hypodermic\$2 needle hypodermic) same ((\$1mu\$1m micron micrometer "1 millimeter" "one millimeter") with (long length)) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 18:27